


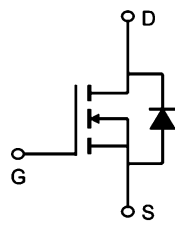


TM100N20HP

N-Channel Enhancement Mosfet

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p><math>V_{DS} = 200V</math> <math>I_D = 100A</math></p> <p><math>R_{DS(ON)} = 17 m\Omega (typ.) @ V_{GS} = 10V</math></p> <p>100% UIS Tested 100% <math>R_g</math> Tested</p> 
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P:TO-220AB

Marking: 100N20 G D S

**Absolute Maximum Ratings:** ( $T_c = 25^\circ C$  unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	200	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>1,6</sup>	100	A
	Continuous Drain Current- $T_c = 100^\circ C$ <sup>1,6</sup>	63	
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	400	
$P_D$	Power Dissipation <sup>4</sup>	272	W
$E_{AS}$	Single pulse avalanche energy <sup>3</sup>	1190	mJ
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55-+175	$^\circ C$

**Thermal Characteristics:**

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case <sup>1</sup>	15	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>1</sup>	62	$^\circ C/W$



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## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	200	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	---	---	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =61A	---	17	22	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =61A	---	---	---	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	3	4	5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	---	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =100°C	---	---	100	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =31A	---	73	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.2	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, I <sub>D</sub> =61A	---	134	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	49.6	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	39.6	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 50V, R <sub>L</sub> =1.25Ω R <sub>G</sub> = 3Ω, V <sub>GS</sub> =10V	---	36.3	---	ns
T <sub>r</sub>	Rise Time		---	9.2	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	64	---	
T <sub>f</sub>	Fall Time		---	6.3	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	---	8826	---	pF
C <sub>oss</sub>	Output Capacitance		---	532	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	148	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	100	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =31A, T <sub>J</sub> =25C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =61A, di/dt=100A/μs,	---	102	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> = 25 C	---	550.3	---	nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.E<sub>AS</sub> condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=40V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

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Typical Characteristics

Figure 1. Output Characteristics

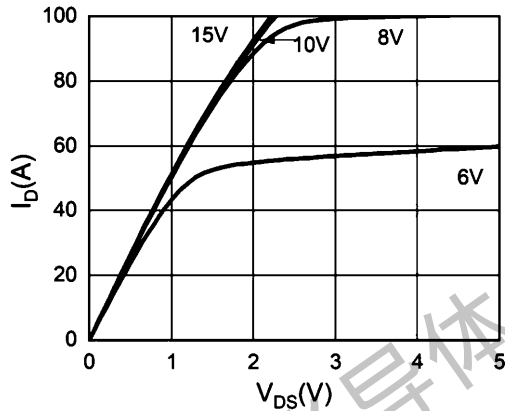


Figure 2. Transfer Characteristics

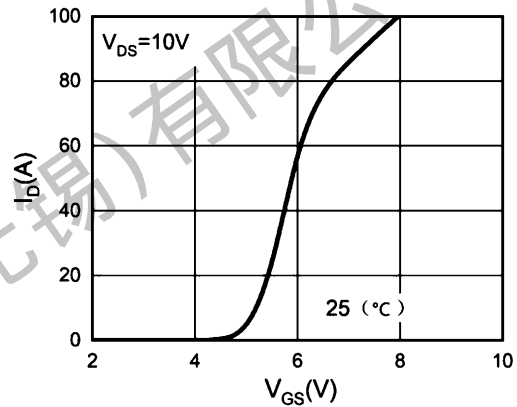


Figure 3. Power Dissipation

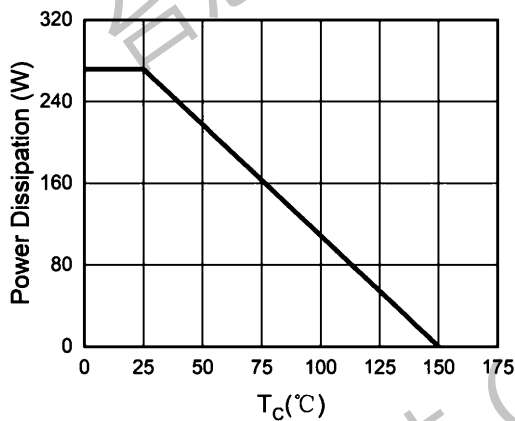


Figure 4. Drain Current

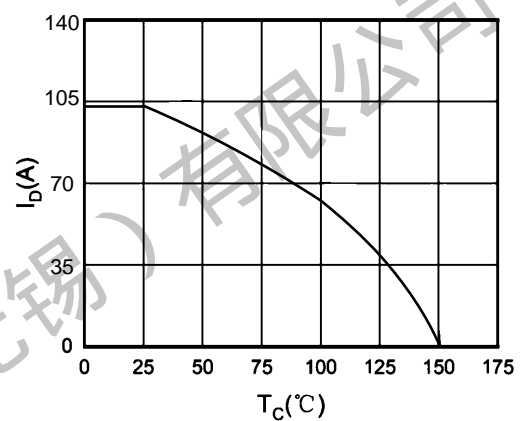


Figure 5.  $BV_{DSS}$  vs Junction Temperature

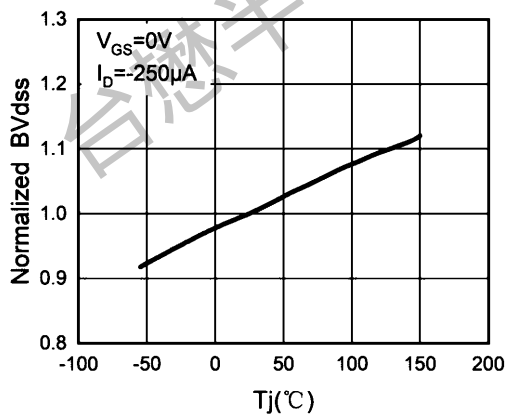
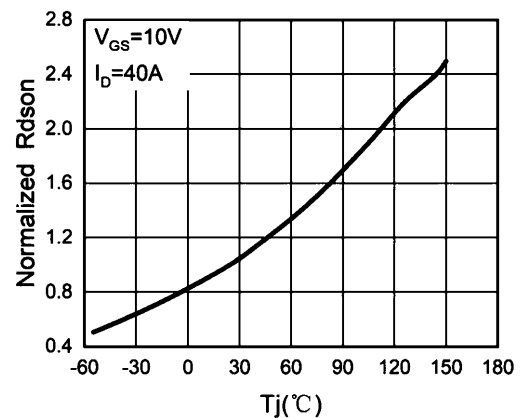


Figure 6.  $R_{DS(ON)}$  vs Junction Temperature





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Figure 7. Gate Charge Waveforms

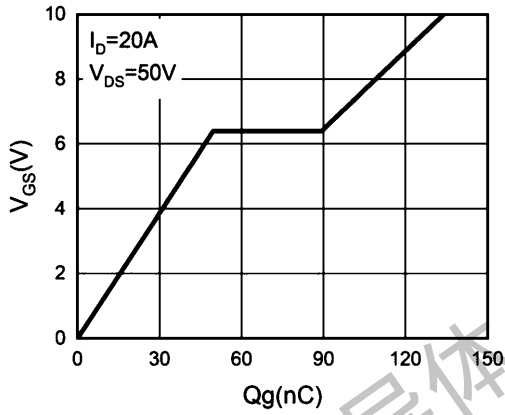


Figure 8. Capacitance

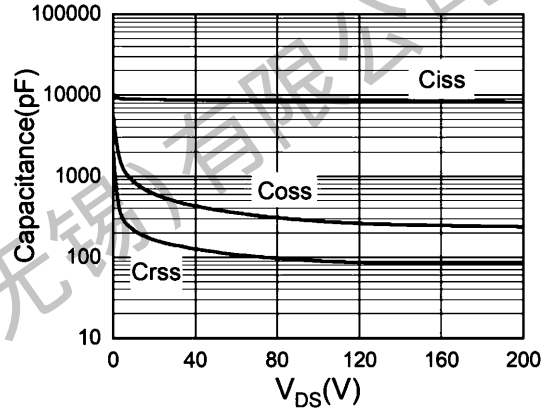


Figure 9. Body-Diode Characteristics

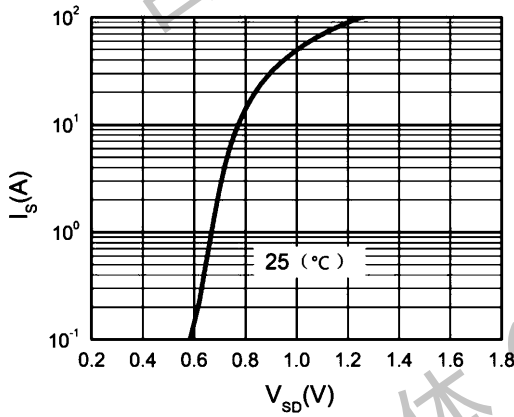
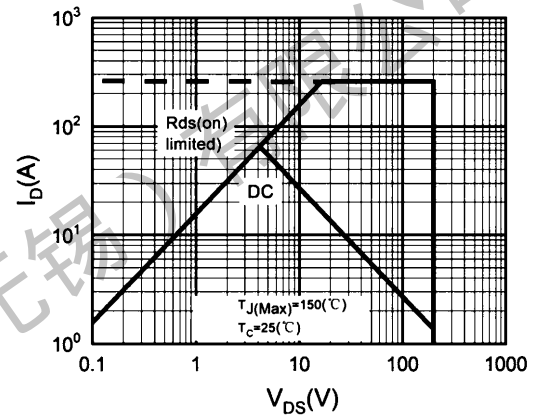


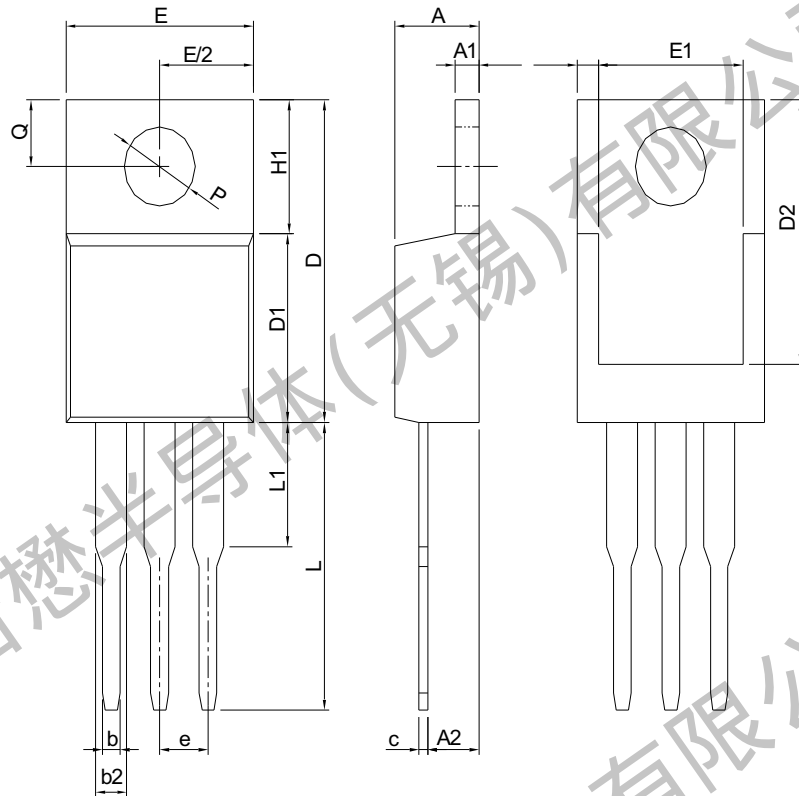
Figure 10. Maximum Safe Operating Area



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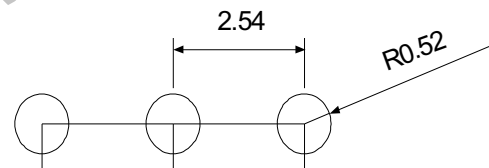
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Package Mechanical Data: TO-220AB



DIMENSIONS	TO-220			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	3.56	4.83	0.140	0.190
A1	0.51	1.40	0.020	0.055
A2	2.03	2.92	0.080	0.115
b	0.38	1.02	0.015	0.040
b2	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.22	16.51	0.560	0.650
D1	8.38	9.02	0.330	0.355
D2	12.19	13.65	0.480	0.537
E	9.65	10.67	0.380	0.420
E1	6.86	8.89	0.270	0.350
e	2.54 BSC		0.100 BSC	
H1	5.84	6.86	0.230	0.270
L	12.70	14.73	0.500	0.580
L1	-	6.35	-	0.250
P	3.53	4.09	0.139	0.161
Q	2.54	3.43	0.100	0.135

RECOMMENDED LAND PATTERN

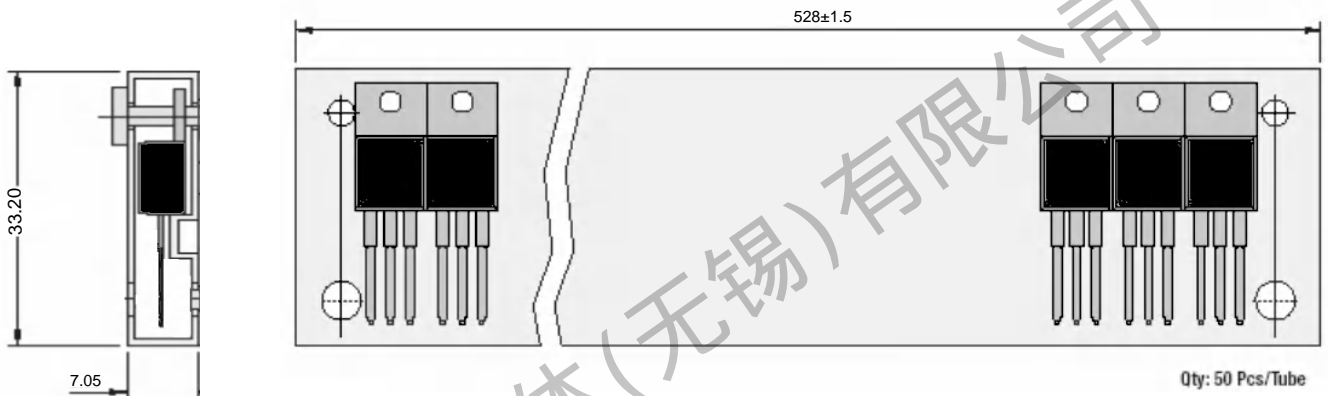


UNIT: mm

Note: Follow JEDEC TO-220 AB.

**TM100N20HP**

**N-Channel Enhancement Mosfet**



All Dimensions are in mm

**1. TO-220AB Packaging**

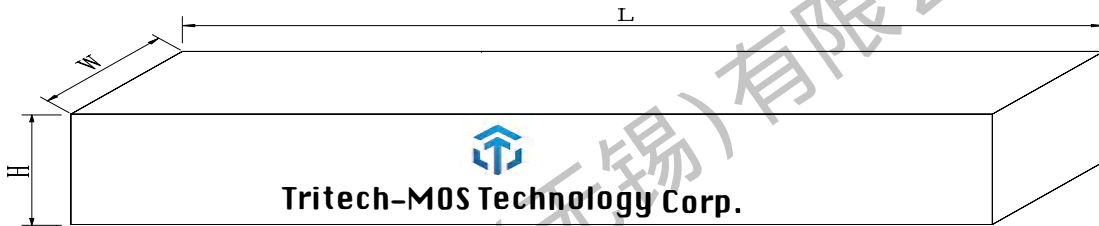
Package	Packing Form	Quantity		
		Tube	Inner Box [kpcs]	Outbox [kpcs]
TO-220AB	Tube Tape	50	5	1



# TM100N20HP

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## Inner Box



Dimension : 580 (L)×154(W) ×49(H) mm

Quantity : 50 ×20Ea = 1Kpcs

## Outer Box



Dimension : 595(L)×285(W) ×185(H) mm

Quantity : 1K×5Ea = 5Kpcs



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Revision history:

Date	Rev	Description	Page
2023.07.20	23.07	Original	